

Title (en)

LOW TEMPERATURE HIGH STRENGTH METAL STACK FOR DIE ATTACHMENT

Title (de)

BEI NIEDRIGER TEMPERATUR HOCHFESTE METALLSTAPEL ZUR CHIPBEFESTIGUNG

Title (fr)

EMPILEMENT EN MÉTAL À HAUTE RÉSISTANCE ET À FAIBLE TEMPÉRATURE POUR FIXATION DE PUCE

Publication

EP 2810307 A1 20141210 (EN)

Application

EP 13743107 A 20130125

Priority

- US 201213361569 A 20120130
- US 2013023041 W 20130125

Abstract (en)

[origin: WO2013116086A1] A light emitting diode structure includes a diode region and a metal stack on the diode region. The metal stack includes a barrier layer on the diode region and a bonding layer on the barrier layer. The barrier layer is between the bonding layer and the diode region. The bonding layer includes gold, tin and nickel. A weight percentage of tin in the bonding layer is greater than 20 percent and a weight percentage of gold in the bonding layer is less than about 75 percent. A weight percentage of nickel in the bonding layer may be greater than 10 percent.

IPC 8 full level

H01L 33/00 (2010.01)

CPC (source: EP)

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Citation (search report)

See references of WO 2013116086A1

Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

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DOCDB simple family (application)

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